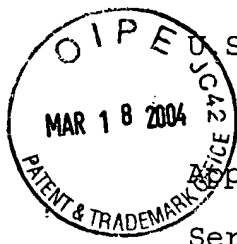


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S.S.N. 10/050,322

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Tsai et al.

Group Art Unit: 1756

Serial No.: 10/050,322

Examiner: N. M. Barreca

Filed: 01/15/2002

In Response to Office Action
Dated: 12/17/2003

For: A BI-LAYER PHOTORESIST DRY DEVELOPMENT AND
REACTIVE ION ETCH METHOD

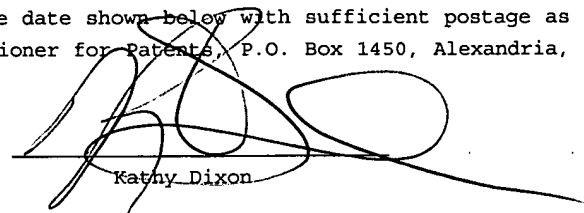
Attorney Docket No.: 67,200-613

Certificate of Mailing

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Va 22313-1450

Date:

MAR. 16/04


Kathy Dixon

RESPONSE TO OFFICE ACTION

Commissioner for Patents
P.O. Box 1450
Alexandria, Va 22313-1450

Dear Sir:

In response to an Office Action mailed 12/17/2003,
please enter the following amendments and consider the following
remarks.